



# Compression Molding System

**Model CPM1150series**



**Compression molding system specialized  
for high-density package molding**



# Compression molding system specialized for high-density package molding

- Optimized for high-density mounting such as HBM4, supporting next-generation narrow-gap structures.
- Adopts a molding process suitable for MUF filling into fine gaps.
- Realization of wafer level molding/panel level molding based on proprietary compression technology.
- Both granular/liquid type resin are available in 1 system. ※CPM1150-HP supports either granular or liquid resin. (preselected configuration)
- Features a proprietary uniform resin dispersion and pattern dispensing system.
- Modular concept to adapt to different production quantities.

CPMseries  
Wafer typeCPMseries  
Panel type

CPM1080-HP

## SPECIFICATION

Items		Unit	Description					
Model		—	CPM1150-V			CPM1150-HP		
Workpiece type		—	Panel · Wafer					
Workpiece size	Panel	mm	□150—320					
	Wafer	mm	φ 320 (Max.)					
Molding compound		—	Granular and Liquid (Switchable)			Granular or Liquid (Selectable)		
Machine time		sec	Approximately 88			Approximately 65		
External dimensions	Number of press modules	module	1	2	1	2	3	4
	Width	mm	3,910	4,590	5,490	6,170	6,850	7,530
	Depth	mm	2,180	2,180	2,168	2,168	2,168	2,168
	Height	mm	1,980	1,980	1,980	1,980	1,980	1,980
Weight		ton	7.0	10.6	10.2	13.8	17.4	21.0
Number of workpieces per cycle		workpiece	1	2	1	2	3	4
Magazine setting space		—	Panel : Input / Output 2 cassette each Wafer : 2 loadport					
Clamp capacity		kN/(tf)	98.0—1,470.0 / 10.0—150.0					
Clamp speed		mm/sec	50 (Max.)					
Release film width		mm	440 (Max.)					

- The figures shown above are based on standard machine specifications.
- The above specification are subject to change without prior notice.
- For special requirements, please consult your local TOWA representative.
- The external dimensions listed are for the granular resin specification.



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